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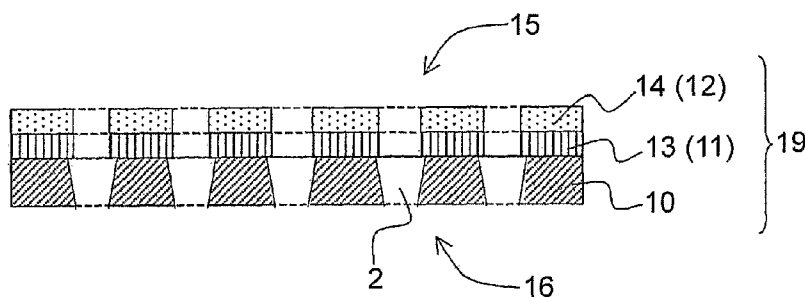
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(54) Title: METHOD FOR FORMING VIA HOLE IN SUBSTRATE FOR FLEXIBLE PRINTED CIRCUIT BOARD

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(57) Abstract: There is provided a method for forming a via hole (2) in a substrate (10) for a flexible printed circuit board, the method being capable of simply forming a via hole having an excellent circularness of an opening portion and high reliability. In a method for forming a via hole in a substrate for a flexible printed circuit board, the method includes the steps: forming a first thin film layer (11) containing metal or alloy and having a thickness of less than 2 μm on one surface (15) of a substrate, disposing a second thin film layer (12) over the first thin film layer (11), selectively removing a portion, corresponding to a region where the via hole (2) is formed, of the second thin film layer (12), etching the first thin film layer (11), and subjecting the substrate (10) to chemical milling to form the via hole (2).

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